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(12) **United States Design Patent**
Morad et al.

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(54) **SOLAR PANEL**

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(**) Term: **15 Years**

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Related U.S. Application Data

(63) Continuation of application No. 29/617,566, filed on Sep. 14, 2017, which is a continuation of application No. 15/359,326, filed on Nov. 22, 2016, now Pat. No. 10,090,430, which is a continuation of application No. PCT/US2015/032472, filed on May 26, 2015, which is a continuation-in-part of application No. 14/674,983, filed on Mar. 31, 2015, now Pat. No.

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(52) **U.S. Cl.**
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(58) **Field of Classification Search**
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CPC H01L 31/0508; H01L 31/0201; H01L 31/0504
See application file for complete search history.

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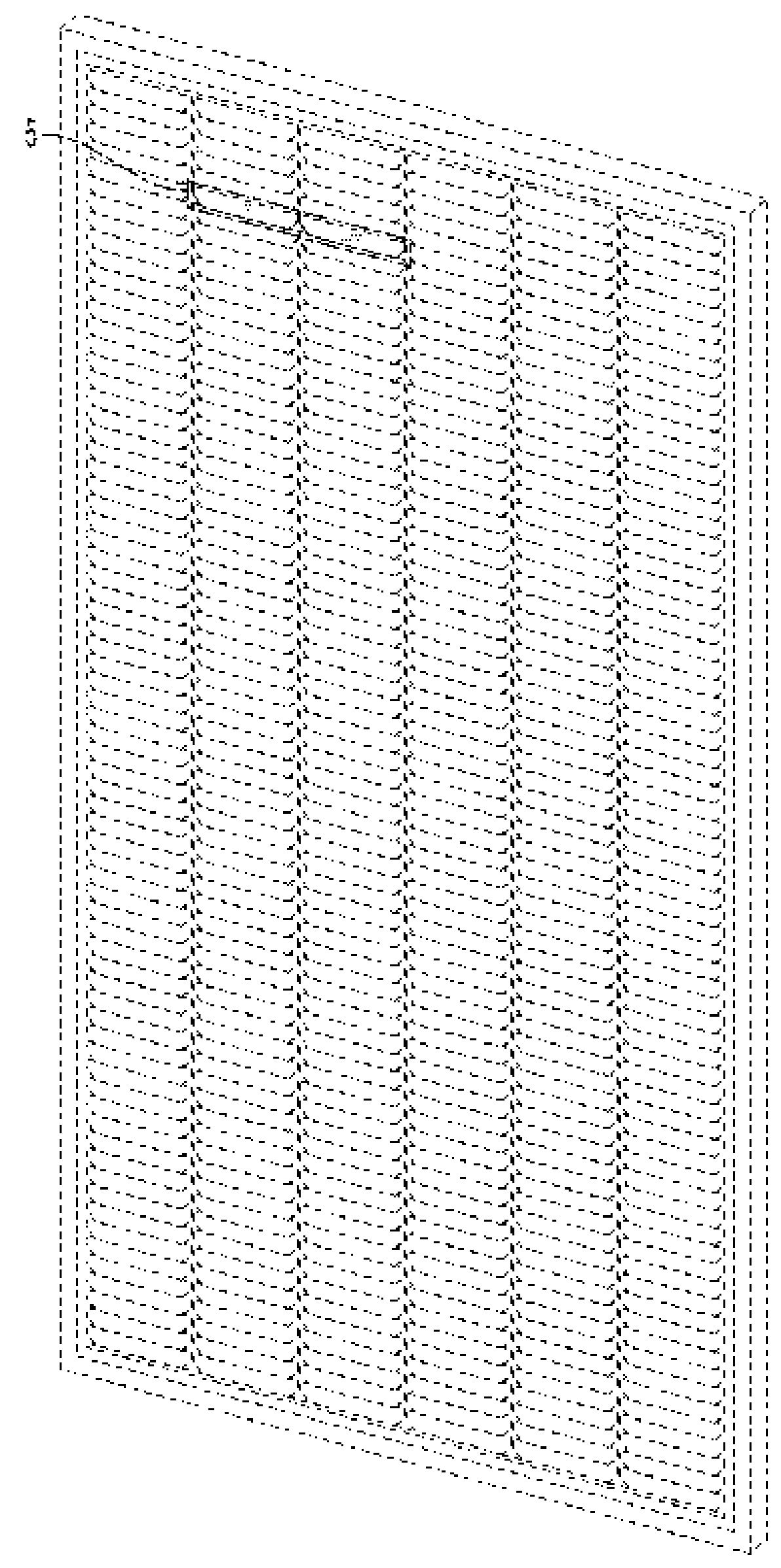
(57) **CLAIM**

The ornamental design for a solar panel, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, and right side perspective view of a solar panel;
FIG. **2** is a front elevational view thereof, the rear elevational view forms no part of the claimed design;
FIG. **3** is a top plan view thereof, the bottom plan view being a mirror image of the top plan view shown;
FIG. **4** is a left side elevational view thereof, the right side elevational view being a mirror image of the left side elevational view shown;
FIG. **5** is a detail view of callout box **5** in FIG. **1**; and,
FIG. **6** is a detail view along line **6-6** in FIG. **2**.
The broken lines shown represent portions of the solar panel that form no part of the claimed design. Where the dot-dash broken lines abut the shaded surface it is understood that those broken lines represent an unclaimed boundary between claimed and unclaimed surfaces. None of the broken lines form any part of the claimed design.

1 Claim, 3 Drawing Sheets



Related U.S. Application Data

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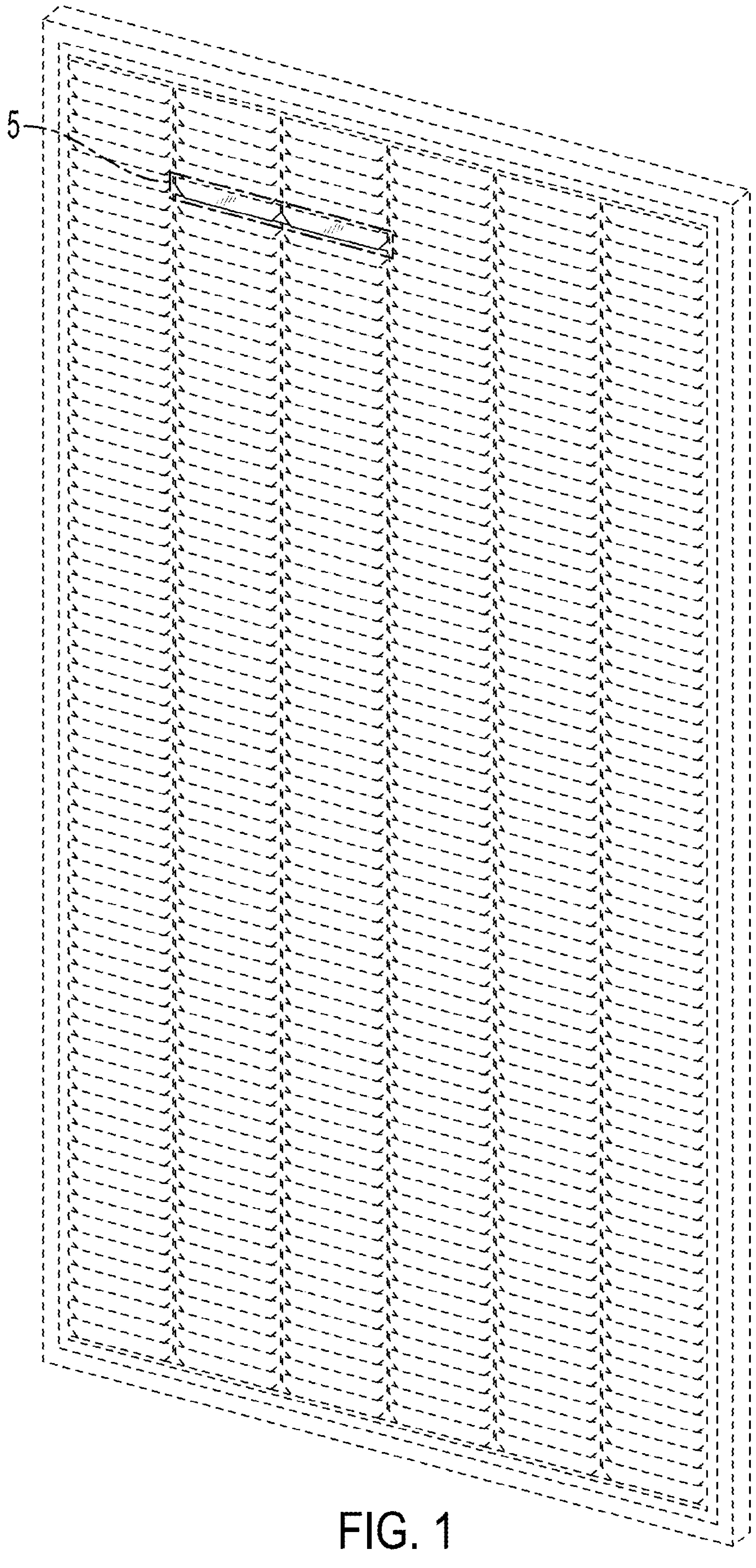

FIG. 1

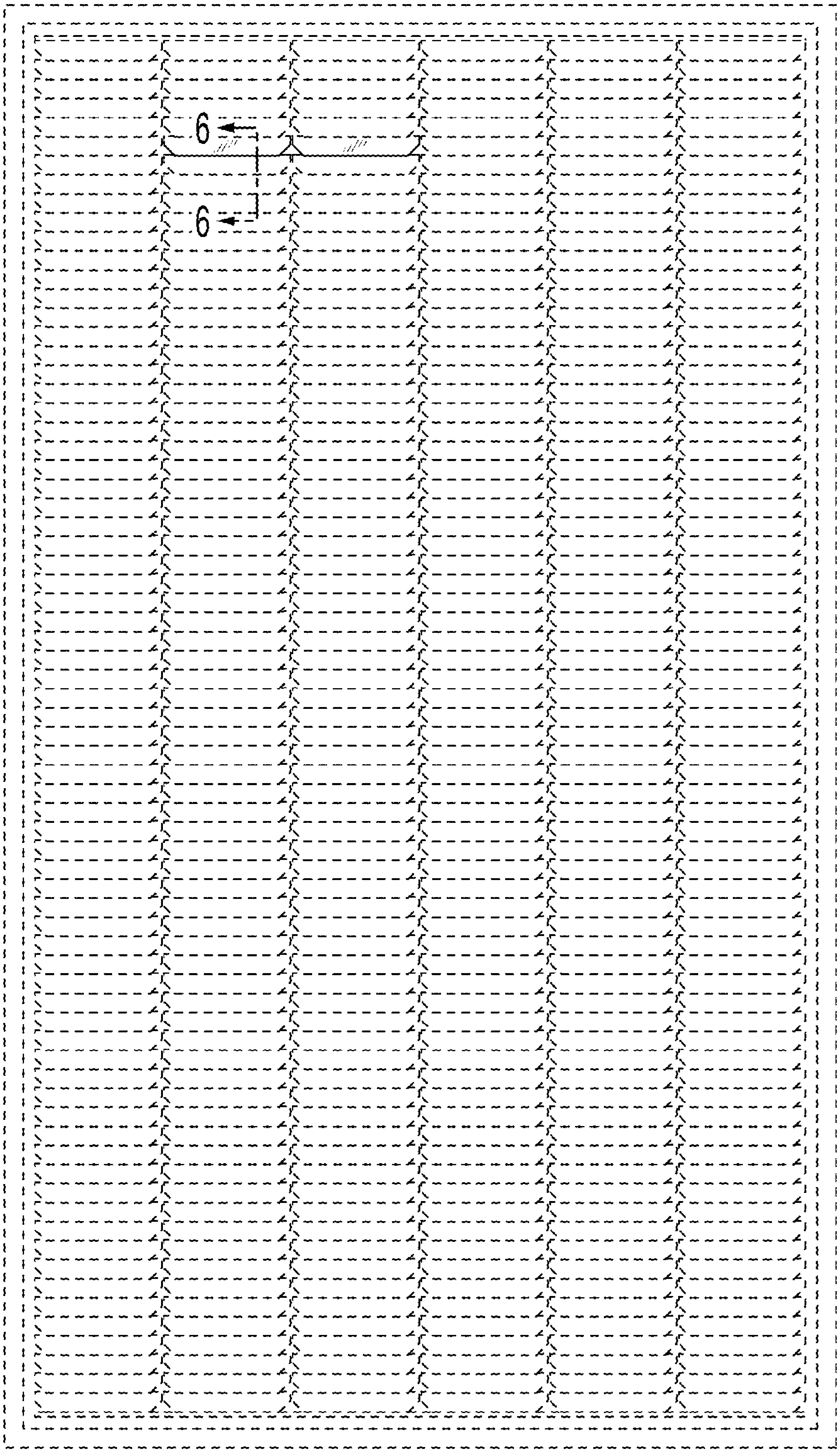

FIG. 2

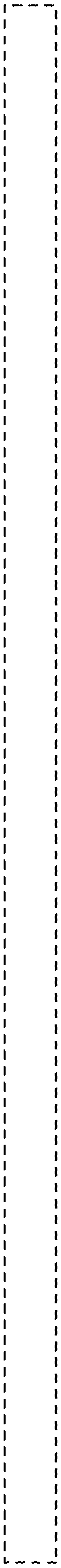

FIG. 4

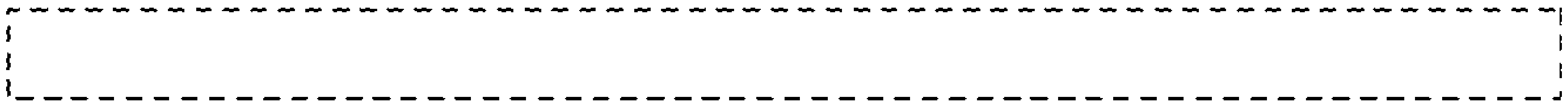

FIG. 3

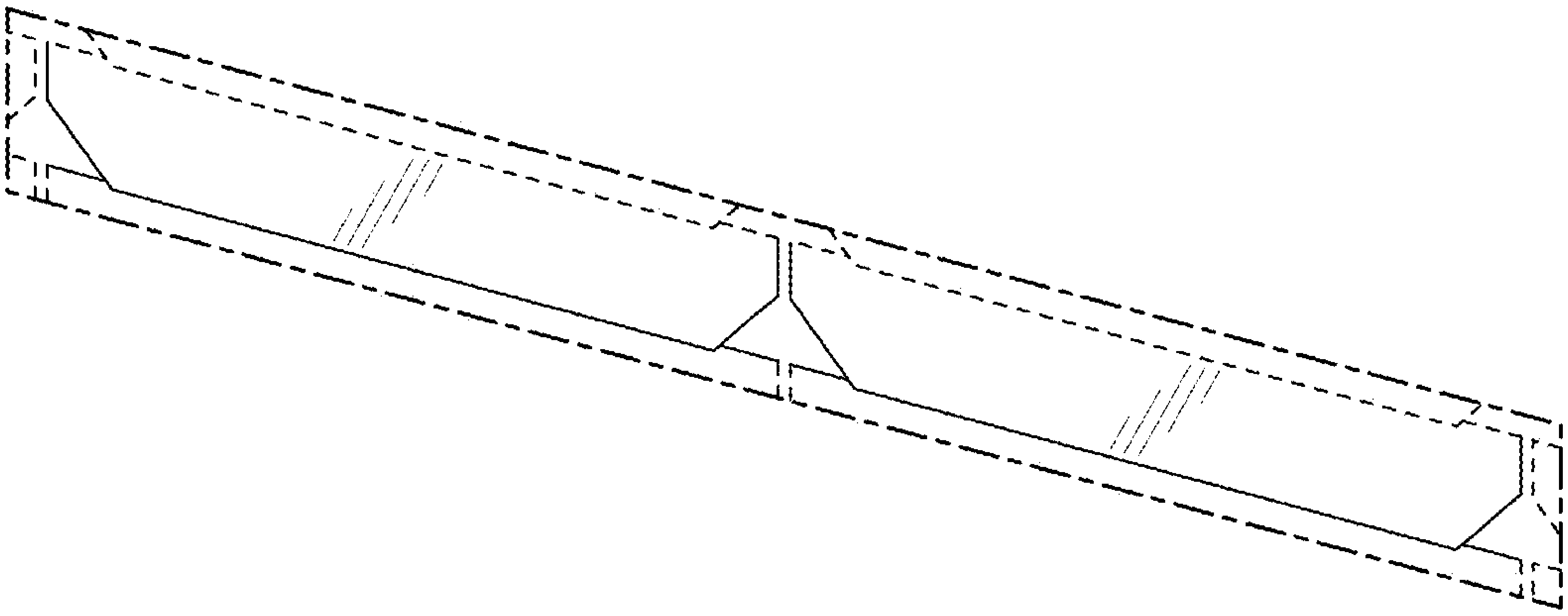

FIG. 5

FIG. 6